

PRELIMINARY DATA SHEET

NEC

PHOTOCOUPLER PS2561D-1,PS2561DL-1 PS2561DL1-1,PS2561DL2-1

DIP PHOTOCOUPLER OPERATING AMBIENT TEMPERATURE 110°C

–NEPOC Series–

DESCRIPTION

The PS2561D-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor.

The PS2561D-1 is in a plastic DIP (Dual In-line Package) and the PS2561DL-1 is lead bending type (Gull-wing) for surface mount.

The PS2561DL1-1 is lead bending type for long creepage distance.

The PS2561DL2-1 is lead bending type for long creepage distance (Gull-wing) for surface mount.

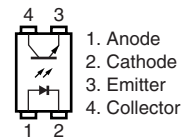
FEATURES

- Operating ambient temperature: 110°C
- High Isolation voltage (BV = 5 000 Vr.m.s.)
- High collector to emitter voltage ($V_{CE0} = 80\text{ V}$)
- High current transfer ratio (CTR = 160% TYP.)
- High-speed switching ($t_r = 3\ \mu\text{s}$ TYP., $t_f = 5\ \mu\text{s}$ TYP.)
- Ordering number of taping product: PS2561DL-1-F3 : 2 000 pcs/reel
: PS2561DL2-1-E3: 1 000 pcs/reel
- Pb-Free product

APPLICATIONS

- Power supply
- Telephone/FAX.
- FA/OA equipment
- Programmable logic controller

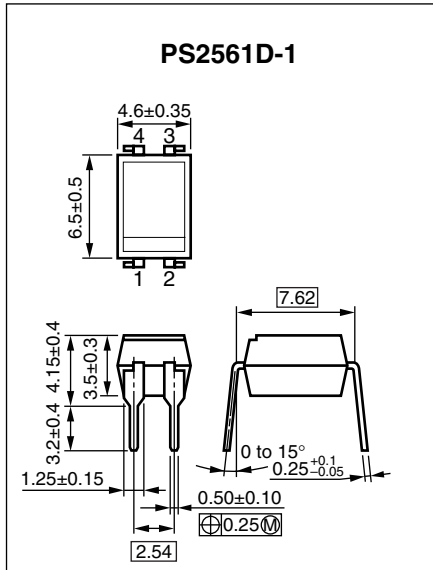
PIN CONNECTION (Top View)



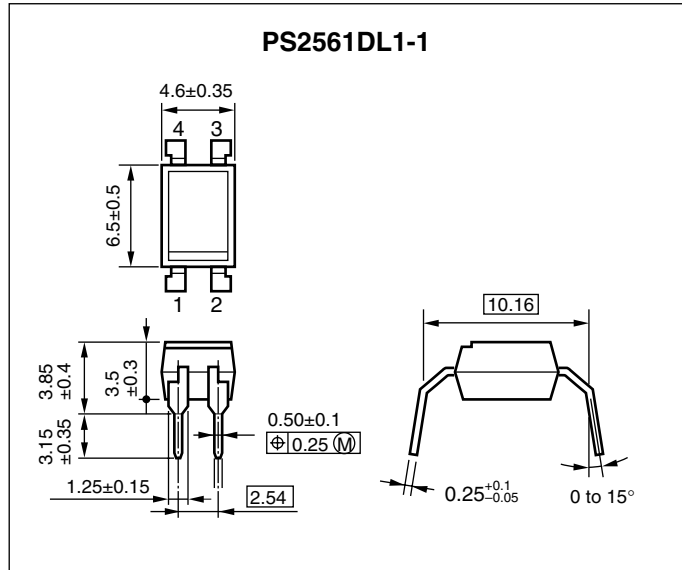
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PACKAGE DIMENSIONS (UNIT : mm)

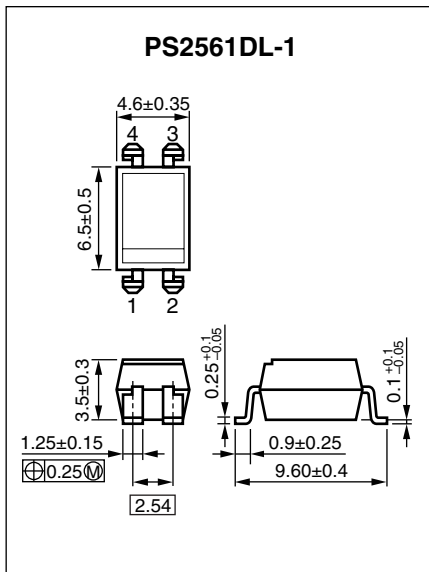
DIP Type



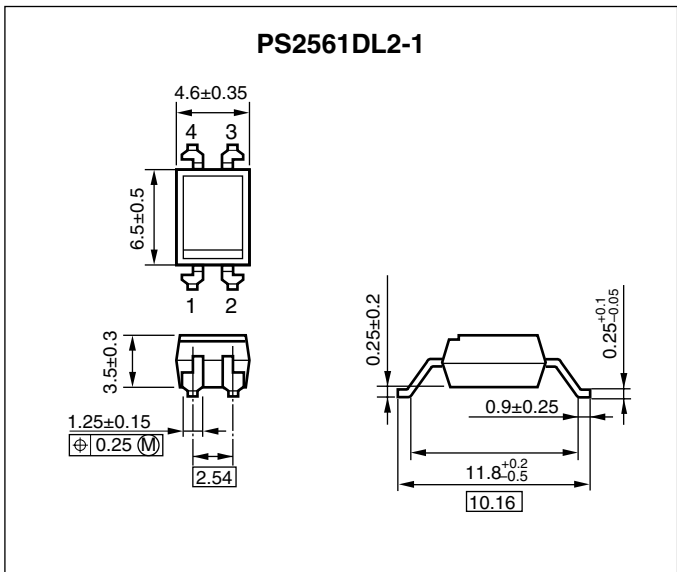
Long Creepage Distance



Lead Bending Type



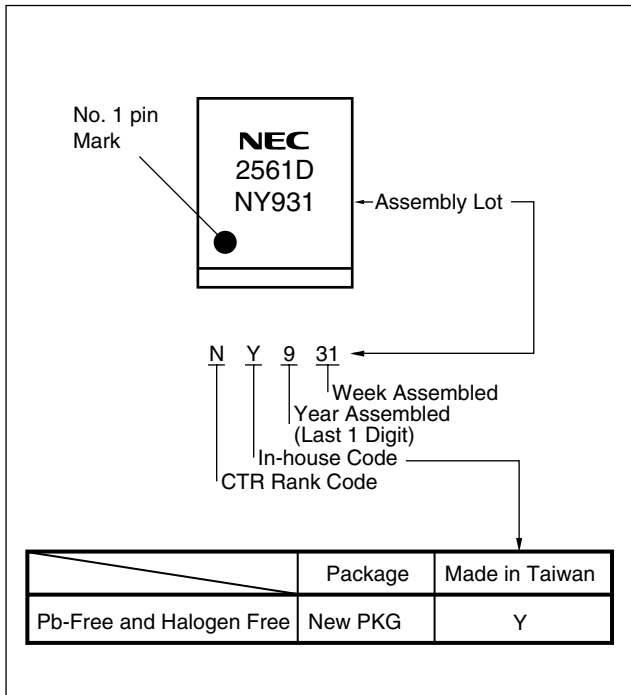
Long Creepage Distance (Gull-Wing)



PHOTOCOUPLER CONSTRUCTION

Parameter	PS2561D-1, PS2561DL-1	PS2561DL1-1, PS2561DL2-1
Air Distance (MIN.)	7 mm	8 mm
Outer Creepage Distance (MIN.)	7 mm	8 mm
Inner Creepage Distance (MIN.)	4 mm	4 mm
Isolation Distance (MIN.)	0.4 mm	0.4 mm

MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}		
PS2561D-1	PS2561D-1Y-A	Special version (Pb-Free and Halogen Free)	Magazine case 100 pcs	Standard products (UL, CSA, BSI, NEMKO, DEMKO, SEMKO, FIMKO awaiting approval)	PS2561D-1		
PS2561DL-1	PS2561DL-1Y-A				PS2561DL-1		
PS2561DL1-1	PS2561DL1-1Y-A				PS2561DL1-1		
PS2561DL2-1	PS2561DL2-1Y-A				PS2561DL2-1		
PS2561DL-1-F3	PS2561DL-1Y-F3-A		Embossed Tape 2 000 pcs/reel	awaiting approval)	PS2561DL-1		
PS2561DL2-1-E3	PS2561DL2-1Y-E3-A		Embossed Tape 1 000 pcs/reel		PS2561DL2-1		
PS2561D-1-V	PS2561D-1Y-V-A		Magazine case 100 pcs	Magazine case 100 pcs	DIN EN60747-5-2 (VDE0884 Part2) awaiting approval (Option)	PS2561D-1	
PS2561DL-1-V	PS2561DL-1Y-V-A					PS2561DL-1	
PS2561DL1-1-V	PS2561DL1-1Y-V-A					PS2561DL1-1	
PS2561DL2-1-V	PS2561DL2-1Y-V-A					PS2561DL2-1	
PS2561DL-1-V-F3	PS2561DL-1Y-V-F3-A					Embossed Tape 2 000 pcs/reel	PS2561DL-1
PS2561DL2-1-V-E3	PS2561DL2-1Y-V-E3-A					Embossed Tape 1 000 pcs/reel	PS2561DL2-1

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Reverse Voltage	V _R	6	V
	Forward Current (DC)	I _F	40	mA
	Power Dissipation Derating	ΔP _D /°C	1.5	mW/°C
	Power Dissipation	P _D	150	mW
	Peak Forward Current ^{*1}	I _{FP}	1	A
Transistor	Collector to Emitter Voltage	V _{CEO}	80	V
	Emitter to Collector Voltage	V _{ECO}	7	V
	Collector Current	I _C	50	mA
	Power Dissipation Derating	ΔP _C /°C	1.5	mW/°C
	Power Dissipation	P _C	150	mW
Isolation Voltage ^{*2}		BV	5 000	Vr.m.s.
Operating Ambient Temperature		T _A	-55 to +110	°C
Storage Temperature		T _{stg}	-55 to +150	°C

*1 PW = 100 μs, Duty Cycle = 1%

*2 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output.
Pins 1-2 shorted together, 3-4 shorted together.

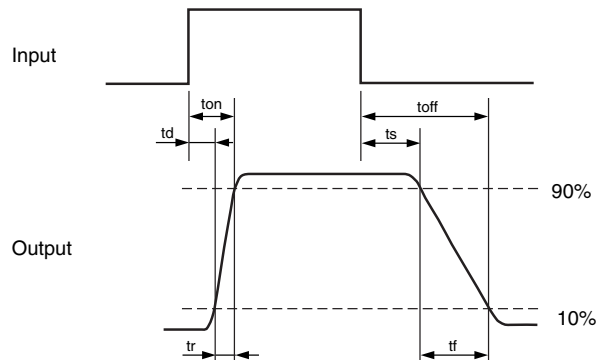
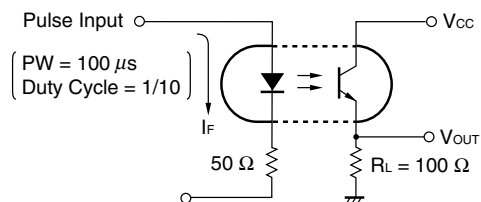
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 10 mA		1.2	1.4	V
	Reverse Current	I _R	V _R = 5 V			5	μA
	Terminal Capacitance	C _t	V = 0 V, f = 1.0 MHz		10		pF
Transistor	Collector to Emitter Dark Current	I _{CEO}	V _{CE} = 48 V, I _F = 0 mA			100	nA
Coupled	Current Transfer Ratio (I _c /I _F) ^{*1}	CTR	I _F = 5 mA, V _{CE} = 5 V	50	160	400	%
			I _F = 1 mA, V _{CE} = 5 V	10	80		
	Collector Saturation Voltage	V _{CE(sat)}	I _F = 10 mA, I _c = 2 mA			0.3	V
	Isolation Resistance	R _{I-O}	V _{I-O} = 1.0 kV _{DC}	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1.0 MHz		0.5		pF
	Rise Time ^{*2}	t _r	V _{CC} = 10 V, I _c = 2 mA, R _L = 100 Ω		3		μs
	Fall Time ^{*2}	t _f			5		

*1 CTR rank

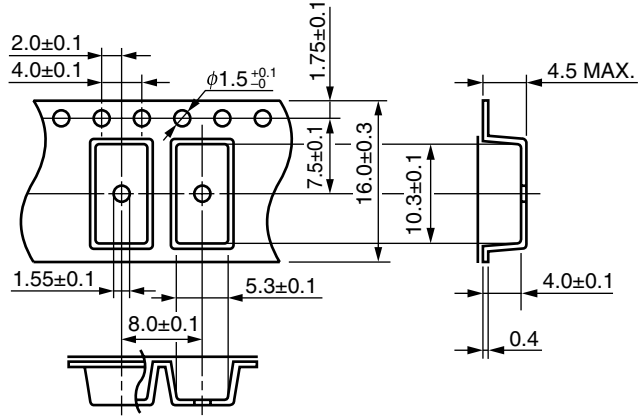
CTR Rank	CTR (%)	Conditions
H	80 to 160	I _F = 5 mA, V _{CE} = 5 V
	16 and larger	I _F = 1 mA, V _{CE} = 5 V
Q	100 to 200	I _F = 5 mA, V _{CE} = 5 V
	20 and larger	I _F = 1 mA, V _{CE} = 5 V
W	130 to 260	I _F = 5 mA, V _{CE} = 5 V
	26 and larger	I _F = 1 mA, V _{CE} = 5 V
L	200 to 400	I _F = 5 mA, V _{CE} = 5 V
	40 and larger	I _F = 1 mA, V _{CE} = 5 V
N	50 to 400	I _F = 5 mA, V _{CE} = 5 V
	10 and larger	I _F = 1 mA, V _{CE} = 5 V

*2 Test circuit for switching time



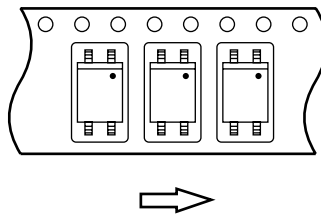
TAPING SPECIFICATIONS (UNIT : mm)

Outline and Dimensions (Tape)

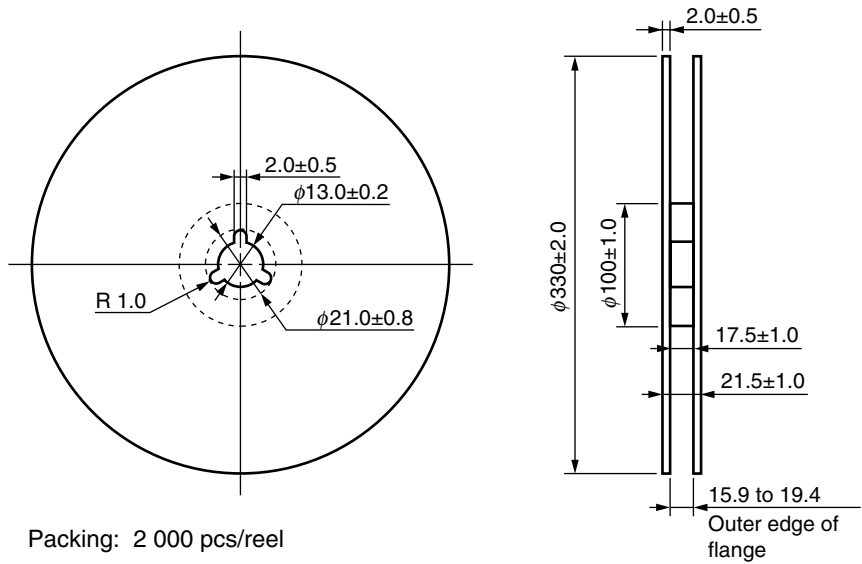


Tape Direction

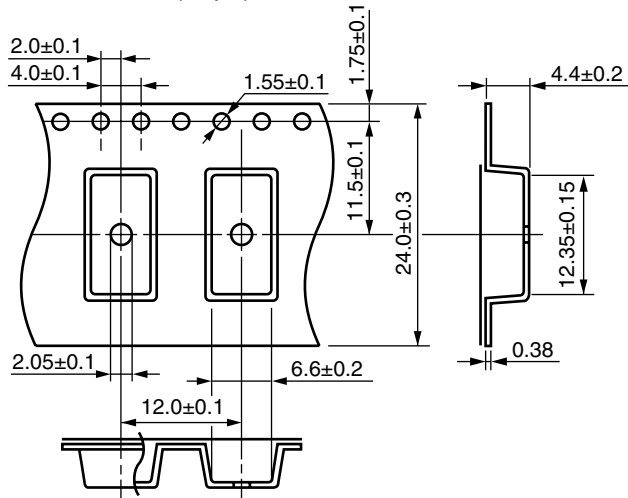
PS2561DL-1-F3



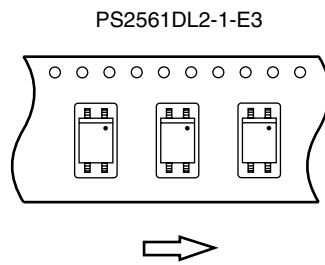
Outline and Dimensions (Reel)



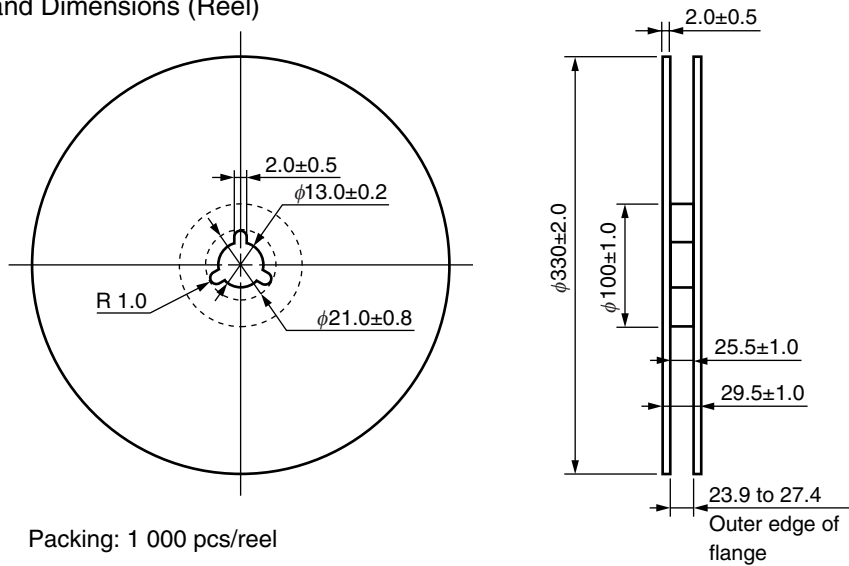
Outline and Dimensions (Tape)



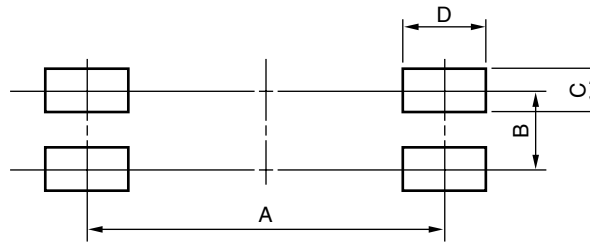
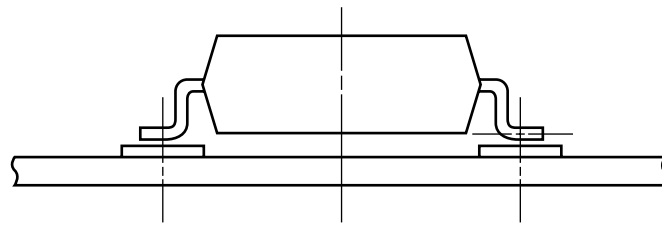
Tape Direction



Outline and Dimensions (Reel)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Part Number	Lead Bending	A	B	C	D
PS2561DL	lead bending type (Gull-wing) for long creepage distance (surface mount)	8.2	2.54	1.7	2.2
PS2561DL2	lead bending type (Gull-wing) for surface mount	10.2	2.54	1.7	2.2

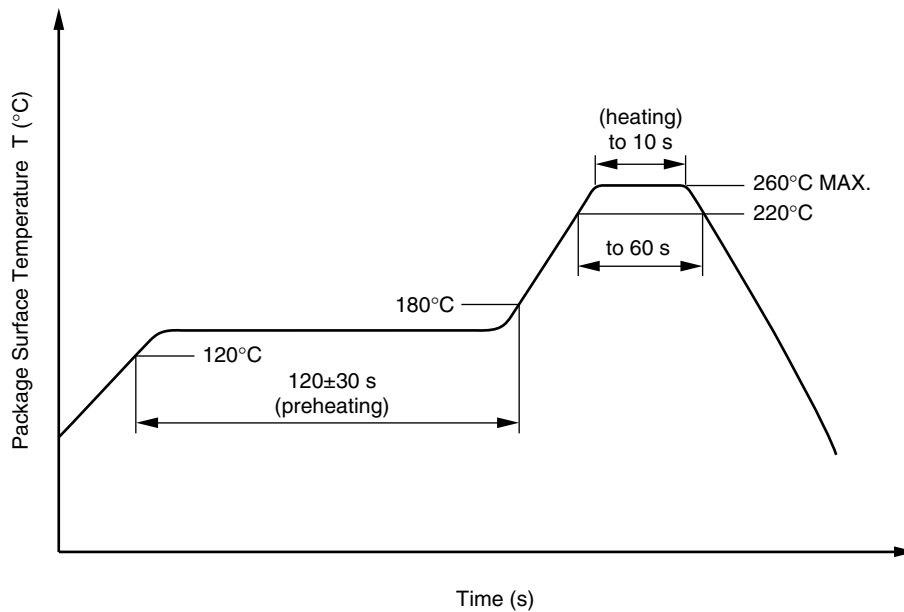
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between corrector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

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